

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. – 31. (Cancelled).

32. (Currently amended) A substrate for ~~mounting~~ semiconductor ~~packages~~~~devices thereon~~ having an insulating supporting member and plural sets of wirings formed on one side of said insulating supporting member, and further comprising:

a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region,

wherein said ~~plural sets of~~ wirings comprise a predetermined wiring pattern including wire-bonding terminals and external connection terminals,

wherein said wire bonding terminals are provided in said semiconductor package region and said external connection terminals are provided only within said semiconductor device mounting region,

wherein openings are provided in said insulating supporting member at points where said external connection terminals are formed, reaching said external connection terminals, and

wherein plural sets of said semiconductor device mounting region and said semiconductor package region are formed on said insulating supporting member~~said substrate includes a plurality of said semiconductor device mounting regions, and~~

wherein said plurality of said semiconductor device mounting regions and semiconductor package regions ~~respectively~~ have blocks of said wirings, each

having a same wiring pattern.

33. – 34. (Cancelled).

35. (Currently amended) The substrate for ~~mounting~~ semiconductor ~~packages~~~~devices thereon~~ according to claim ~~32~~33, wherein said wire-bonding terminal comprises a nickel layer and a gold plate layer on its surface.

36. (Currently amended) The substrate for ~~mounting~~ semiconductor ~~packages~~~~devices thereon~~ according to claim ~~32~~33,
wherein ~~said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and said external connection terminals are arranged in a grid pattern at positions corresponding to a semiconductor device mounting region and a semiconductor package region of said substrate.~~

37. (Currently amended) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for ~~mounting the semiconductor~~ ~~packages~~~~device thereon~~ according to claim ~~32~~33 by employing a die-bonding material,

electrically connecting each of the semiconductor ~~devices~~~~device~~ with the wire-bonding terminals by wire-bonding,

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sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for ~~mounting the semiconductor packages~~ device ~~thereon~~ and said sealing resin in one operation to be separated into the individual semiconductor package.

38. – 40. (Cancelled).

41. (New) The substrate for semiconductor packages according to claim 32, wherein said plural sets of wirings are formed only on said one side of said insulating supporting member.